

RoHS

N-Channel 650V (D-S) Super Junction Power MOSFET

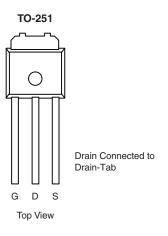
PRODUCT SUMMARY					
V _{DS} (V) at T _J max.	650				
R _{DS(on)} at 25 °C (Ω)	V _{GS} = 10 V 0.42				
Q _g max. (nC)	38				
Q _{gs} (nC)	4				
Q _{gd} (nC)	4.2				
Configuration	Single				

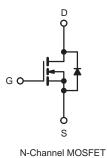
FEATURES

- Low figure-of-merit (FOM) Ron x Qa
- Low input capacitance (Ciss)
- Reduced switching and conduction losses
- Ultra low gate charge (Q_q)
- Avalanche energy rated (UIS)

APPLICATIONS

- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
 - High-intensity discharge (HID)
 - Fluorescent ballast lighting
- Industrial





ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C, unless otherwise PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-Source Voltage			V _{DS}	650		
Gate-Source Voltage			V _{GS}	± 30	V	
Continuous Drain Current (T 150 °C)	V at 10 V	T _C = 25 °C	- I _D -	11		
Continuous Drain Current ($T_J = 150 \ ^{\circ}C$)	V _{GS} at 10 V	T _C = 100 °C		9.7	А	
Pulsed Drain Current ^a	I _{DM}	55				
Linear Derating Factor				1.67/1.5/0.3	W/°C	
Single Pulse Avalanche Energy ^b			E _{AS}	132	mJ	
Maximum Power Dissipation			P _D	83/83/31	W	
Operating Junction and Storage Temperature Range			T _J , T _{stg}	-55 to +150	°C	
Drain-Source Voltage Slope	T _J = 1	125 °C		50		
Reverse Diode dV/dt d			dV/dt	3.1	V/ns	
Soldering Recommendations (Peak Temperature) c	for	10 s		300	°C	

Notes

a. Repetitive rating; pulse width limited by maximum junction temperature. b. $V_{DD} = 50$ V, starting T_J = 25 °C, L = 28.2 mH, R_g = 25 Ω , I_{AS} = 4.5 A.

c. 1.6 mm from case.

d. $I_{SD} \leq I_D$, dI/dt = 100 A/µs, starting T_J = 25 °C.



THERMAL RESISTANCE RATI	NGS							
PARAMETER	SYMBOL	TYP.		MAX.		UNIT		
Maximum Junction-to-Ambient	R _{thJA}	-	- 60			°0.00		
Maximum Junction-to-Case (Drain)	R _{thJC}	- 0.6				°C/W		
SPECIFICATIONS ($T_J = 25 \text{ °C}$, u	nless otherwi	se noted)						
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT	
Static		•			•			
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} =	= 0 V, I _D =	250 µA	650	-	-	V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Reference	e to 25 °C,	$I_D = 1 \text{ mA}$	-	0.65	-	V/°C
Gate-Source Threshold Voltage (N)	V _{GS(th)}	V _{DS} =	= V _{GS} , I _D =	250 µA	2	-	4	V
Onto Onima Lankana	1	$V_{GS} = \pm 20 V$		V	-	-	± 100	nA
Gate-Source Leakage	I _{GSS}		$V_{GS} = \pm 30 \text{ V}$		-	-	± 1	μA
		V _{DS} = 650 V, V _{GS} = 0 V		-	-	1		
Zero Gate Voltage Drain Current	IDSS	V _{DS} = 520 V	V _{DS} = 520 V, V _{GS} = 0 V, T _J = 125 °C		-	-	10	μA
Drain-Source On-State Resistance	R _{DS(on)}	$V_{GS} = 10 V$		I _D = 5 A	-	0.42	-	Ω
Forward Transconductance	g fs	$V_{DS} = 30 \text{ V}, \text{ I}_{D} = 5 \text{ A}$		-	16	-	S	
Dynamic					•			
Input Capacitance	C _{iss}	$V_{GS} = 0 V,$ $V_{DS} = 100 V,$ f = 1 MHz		-	680	-	pF	
Output Capacitance	C _{oss}			-	140	-		
Reverse Transfer Capacitance	C _{rss}			-	5	-		
Effective Output Capacitance, Energy Related ^a	C _{o(er)}	$V_{DS} = 0$ V to 520 V, $V_{GS} = 0$ V		-	63	-		
Effective Output Capacitance, Time Related ^b	C _{o(tr)}			-	113	-		
Total Gate Charge	Qg	$V_{GS} = 10 \text{ V}$ $I_D = 5 \text{ A}, V_{DS} = 520 \text{ V}$		-	38	56	nC	
Gate-Source Charge	Q _{gs}			-	4	-		
Gate-Drain Charge	Q _{gd}				-	4.5	-	
Turn-On Delay Time	t _{d(on)}	$V_{DD} = 520 \text{ V}, \text{ I}_D = 5 \text{ A},$ $V_{GS} = 10 \text{ V}, \text{ R}_g = 9.1 \Omega$ f = 1 MHz, open drain		-	13	25	ns	
Rise Time	t _r			-	11	35		
Turn-Off Delay Time	t _{d(off)}			-	81	90		
Fall Time	t _f			-	25	40		
Gate Input Resistance	Rg	T = 1	whz, ope	n urain	-	3.5	-	Ω
Drain-Source Body Diode Characteristic	S				1			
Continuous Source-Drain Diode Current	I _S	MOSFET symbol showing the integral reverse p - n junction diode		-	-	11	А	
Pulsed Diode Forward Current	I _{SM}			-	-	55	~	
Diode Forward Voltage	V _{SD}	T _J = 25 °C, I _S = 5 A, V _{GS} = 0 V		-	-	1.5	V	
Reverse Recovery Time	t _{rr}	$T_{J} = 25 \text{ °C, } I_{F} = I_{S} = 5 \text{ A,}$ dl/dt = 100 A/ μ s, V _R = 400 V		-	270	-	ns	
Reverse Recovery Charge	Q _{rr}			-	3.3	-	μC	
Reverse Recovery Current	I _{RRM}			-	30	_	A	

Notes

a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} . b. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} .



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

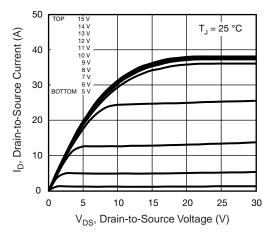


Fig. 1 - Typical Output Characteristics

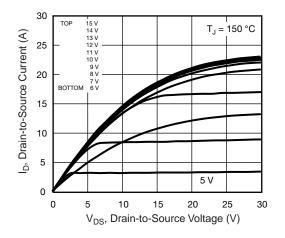


Fig. 2 - Typical Output Characteristics

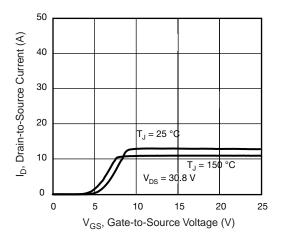


Fig. 3 - Typical Transfer Characteristics

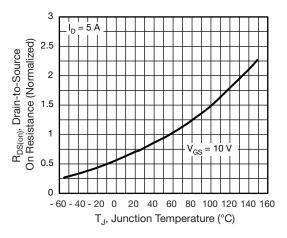


Fig. 4 - Normalized On-Resistance vs. Temperature

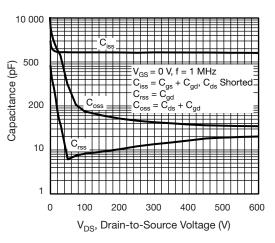


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

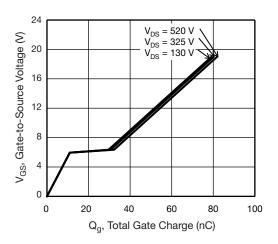


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

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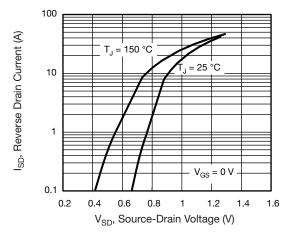
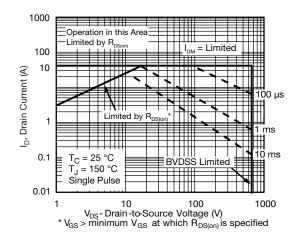


Fig. 7 - Typical Source-Drain Diode Forward Voltage





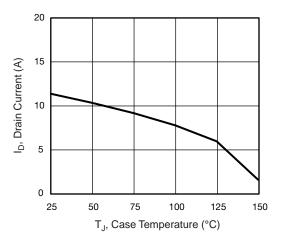


Fig. 9 - Maximum Drain Current vs. Case Temperature

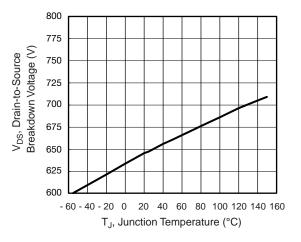


Fig. 10 - Temperature vs. Drain-to-Source Voltage

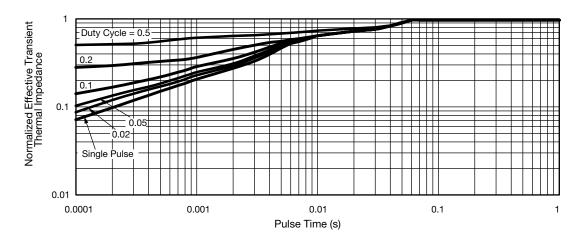


Fig. 11 - Normalized Thermal Transient Impedance, Junction-to-Case



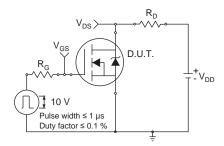


Fig. 12 - Switching Time Test Circuit

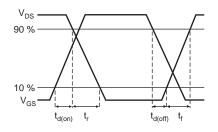


Fig. 13 - Switching Time Waveforms

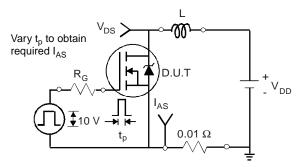


Fig. 14 - Unclamped Inductive Test Circuit

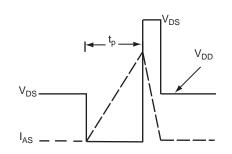


Fig. 15 - Unclamped Inductive Waveforms

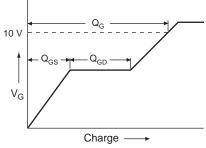


Fig. 16 - Basic Gate Charge Waveform

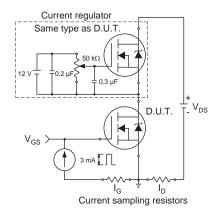
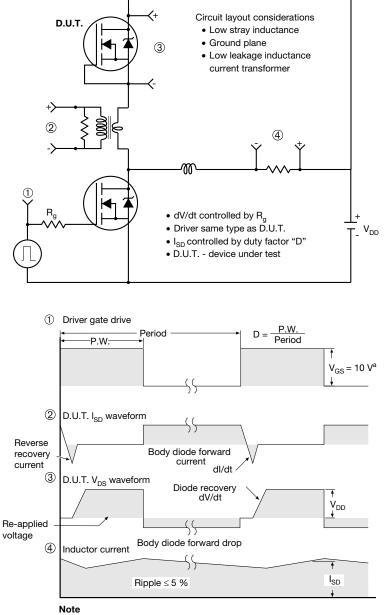


Fig. 17 - Gate Charge Test Circuit



Peak Diode Recovery dV/dt Test Circuit



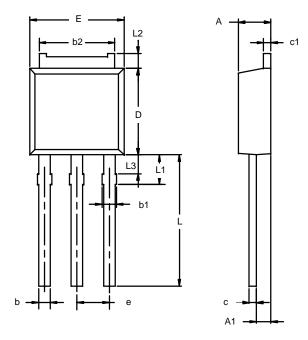
a. $V_{GS} = 5$ V for logic level devices

Fig. 18 - For N-Channel

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TO-251AA



	MILLIN	IETERS	INCHES		
Dim	Min	Max	Min	Max	
Α	2.21	2.38	0.087	0.094	
A1	0.89	1.14	0.035	0.045	
b	0.71	0.89	0.028	0.035	
b1	0.76	1.14	0.030	0.045	
b2	5.23	5.43	0.206	0.214	
С	0.46	0.58	0.018	0.023	
c1	0.46	0.58	0.018	0.023	
D	5.97	6.22	0.235	0.245	
Е	6.48	6.73	0.255	0.265	
е	2.28 BSC		0.090 BSC		
L	3.89	9.53	0.153	0.375	
L1	1.91	2.28	0.075	0.090	
L2	0.89	1.27	0.035	0.050	
L3	1.15	1.52	0.045	0.060	

Note: Dimension L3 is for reference only.



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